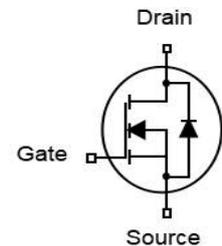
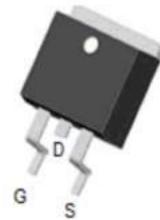


## Features

- N-Channel
- 100% Avalanche Tested
- Reliable and Rugged
- Lead-Free and Green Devices Available
- RoHS Compliant
- 100% EAS Tested

$V_{DS}$	100	V
$R_{DS(on),TYP}@ V_{GS}=10V$	3.2	m $\Omega$
$I_D$	180	A

**TO-263**


Part ID	Package Type	Marking	Packing
ZTG032N10B	TO-263	ZTG032N10B	1000pcs/Reel

## Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ , unless otherwise specified

Symbol	Parameter	Rating	Unit	
<b>Common Ratings (<math>T_c=25^\circ\text{C}</math> Unless Otherwise Noted)</b>				
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	100	V	
$T_J$	Maximum Junction Temperature	175	$^\circ\text{C}$	
$T_{STG}$	Storage Temperature Range	-55 to 175	$^\circ\text{C}$	
$I_{DM}$	Drain Current-Continuous@ Current-Pulsed (Note 1)	$T_c = 25^\circ\text{C}$ 720	A	
<b>Mounted on Large Heat Sink</b>				
$I_D$	Drain Current-Continuous	$T_c = 25^\circ\text{C}$	180	A
		$T_c = 100^\circ\text{C}$	127	A
$P_D$	Maximum Power Dissipation	$T_c = 25^\circ\text{C}$	220	W
		$T_c = 100^\circ\text{C}$	110	W
$R_{\theta JC}$	Thermal Resistance-Junction to Case	0.68	$^\circ\text{C/W}$	
$R_{\theta JA}$	Thermal Resistance Junction-Ambient (Note 2)	62.5	$^\circ\text{C/W}$	
<b>Drain-Source Avalanche Ratings</b>				
EAS	Avalanche Energy, Single Pulsed (Note 3)	720	mJ	

**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ T<sub>J</sub>=25°C (unless otherwise stated)</b>						
V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V	--	--	1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	3.0	4.0	V
R <sub>DS(on)</sub>	Drain-Source On-State Resistance <sup>(Note 4)</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =50A	--	3.2	4.0	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, f=0.5MHz	--	7110	--	pF
C <sub>oss</sub>	Output Capacitance		--	2411	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	182	--	pF
R <sub>g</sub>	Gate Resistance f=1MHz	f=1MHz	--	2.1	--	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =80V, I <sub>D</sub> =50A, V <sub>GS</sub> =10V	--	113	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	40	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	29	--	nC
<b>Switching Characteristics</b>						
T <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =50V, I <sub>D</sub> =50A, R <sub>G</sub> =4Ω, V <sub>GS</sub> =10V	--	27	--	ns
T <sub>r</sub>	Turn-on Rise Time		--	97	--	ns
T <sub>d(off)</sub>	Turn-Off Delay Time		--	69	--	ns
T <sub>f</sub>	Turn-Off Fall Time		--	84	--	ns
<b>Source- Drain Diode Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
I <sub>SD</sub>	Source-Drain Current (Body Diode)		--	--	180	A
V <sub>SD</sub>	Forward on voltage <sup>(Note 4)</sup>	I <sub>S</sub> =50A, V <sub>GS</sub> =0V	--	--	1.3	V
T <sub>rr</sub>	Reverse Recovery Time	T <sub>J</sub> =25°C, I <sub>F</sub> =50A,	--	79	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt=100A/μs	--	191	--	nC

**Notes**

1. Repetitive rating ; pulse width limited by max. junction temperature.
2. Surface mounted on FR -4 board.
3. Limited by T<sub>Jmax</sub> , starting T<sub>J</sub>=25°C, L = 0.3mH, V<sub>DS</sub>=80V, V<sub>GS</sub> =10V.
4. Pulse test , pulse width ≤ 300us, duty cycle ≤ 2%

Typical Electrical and Thermal Characteristics

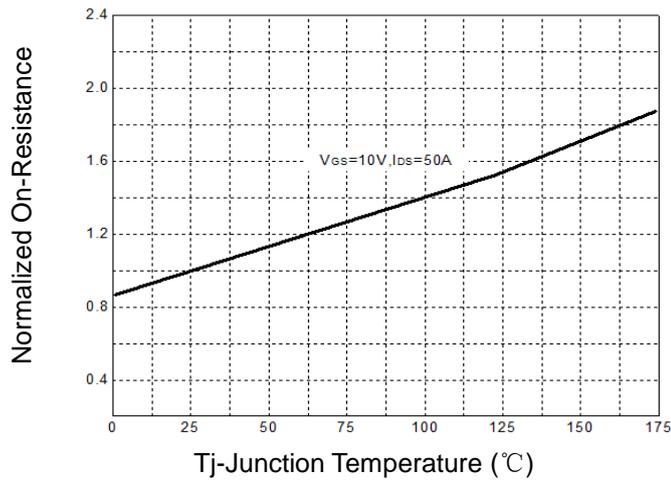


Figure 1: On-Resistance vs. Temperature

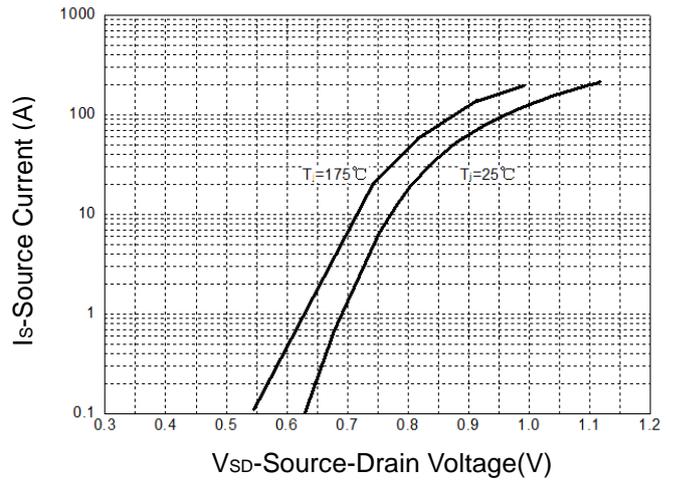


Figure 4: Source-Drain Diode Forward

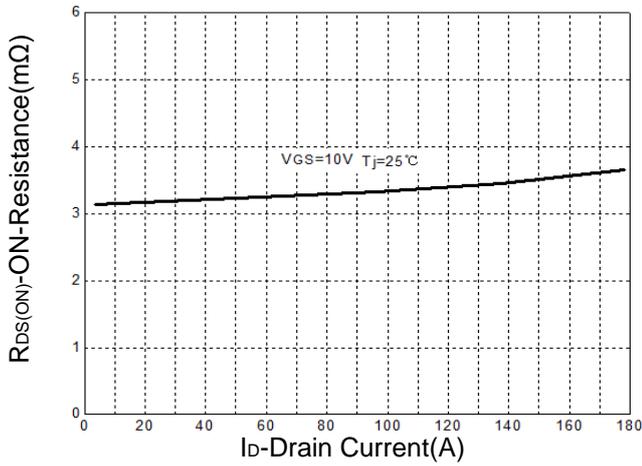


Figure 2: Drain-Source On Resistance

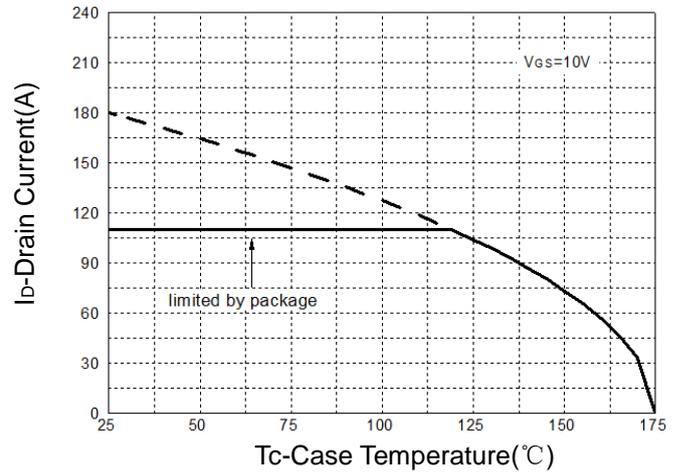


Figure 5: Drain Current

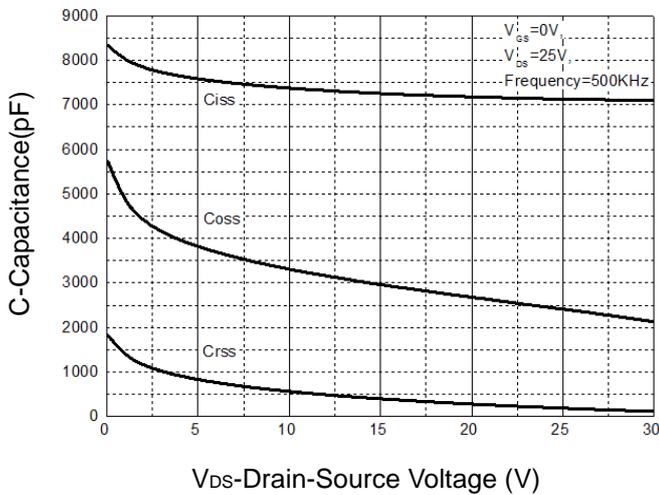


Figure 3: Capacitance Characteristics

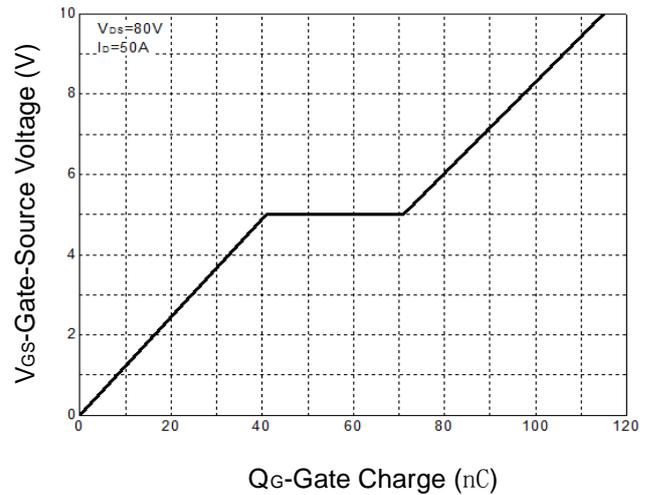


Figure 6: Gate Charge Characteristics

Typical Electrical and Thermal Characteristics

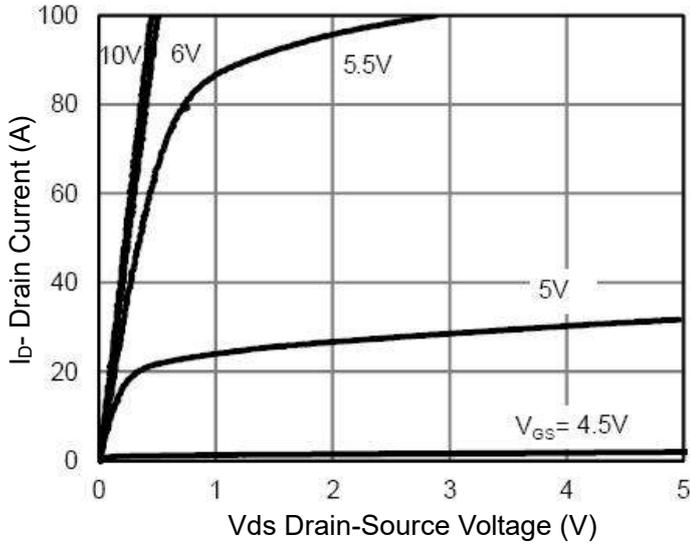


Figure 7: Output Characteristics

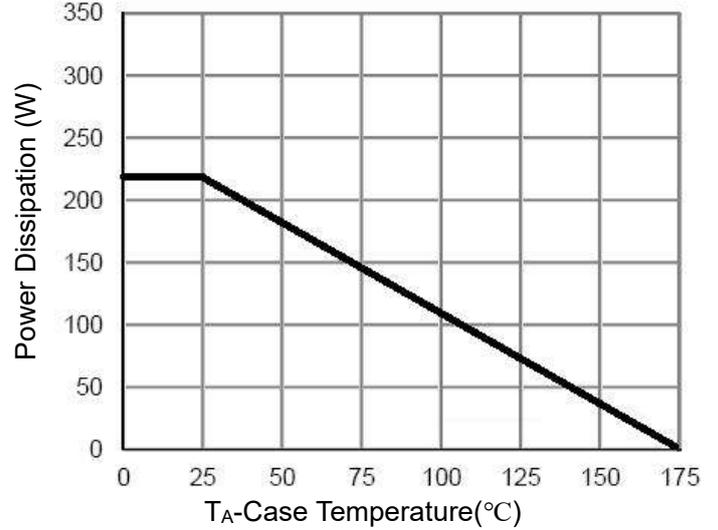


Figure 9: Power De-rating

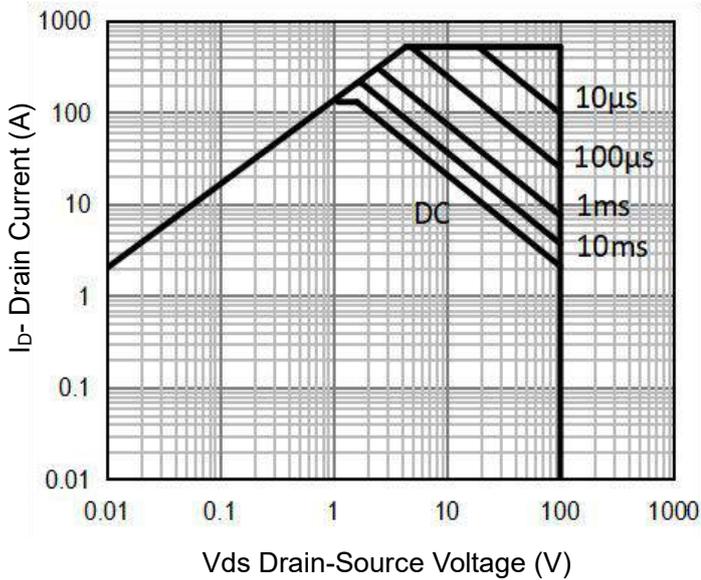


Figure 8: Safe Operation Area

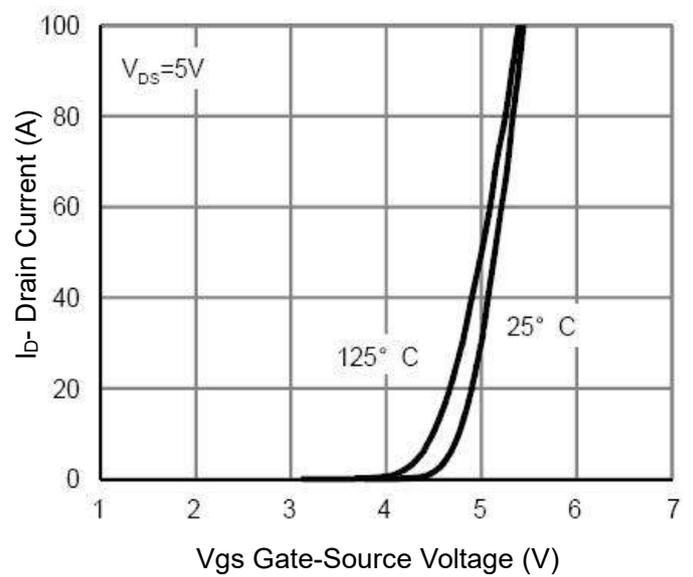


Figure 10: Transfer Characteristics

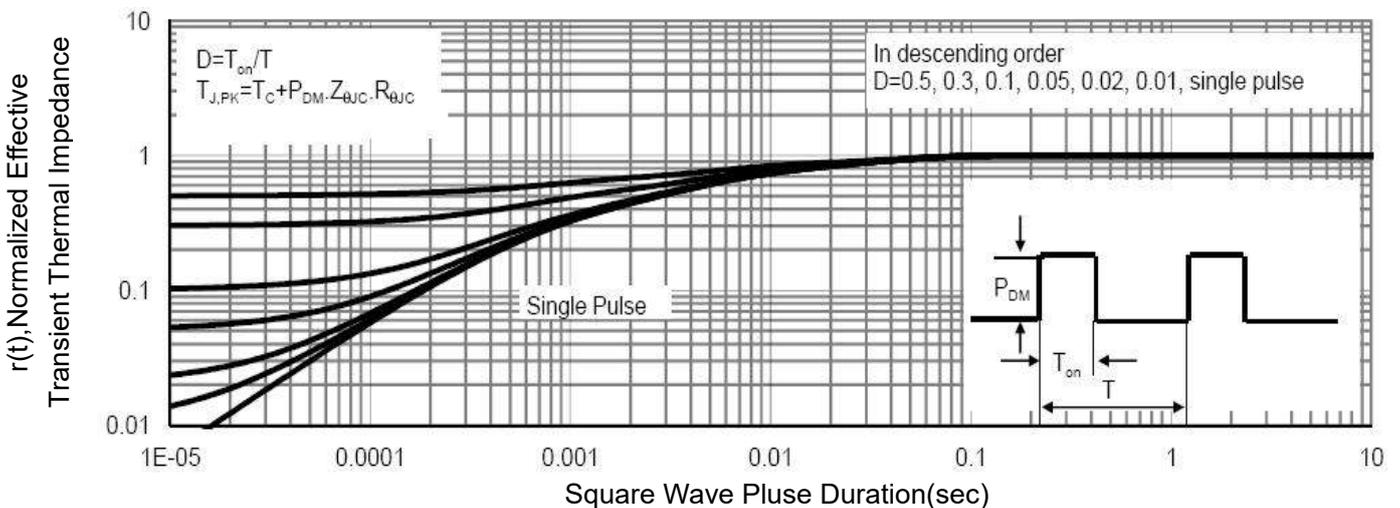


Figure 11: Normalized Maximum Transient Thermal Impedance

Figure A: Gate Charge Test Circuit and Waveform

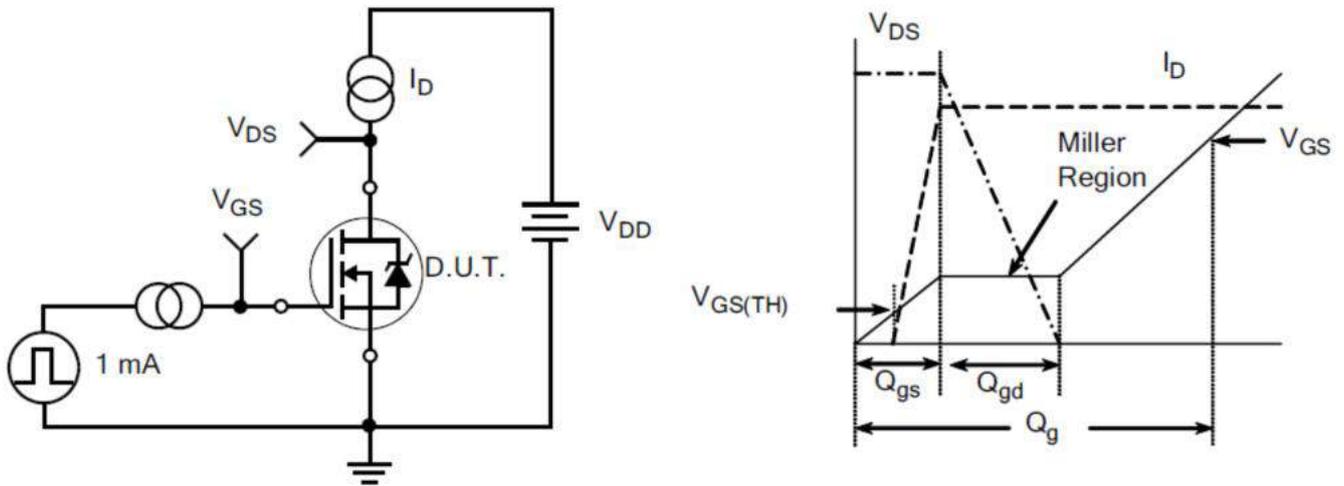


Figure B: Resistive Switching Test Circuit and Waveform

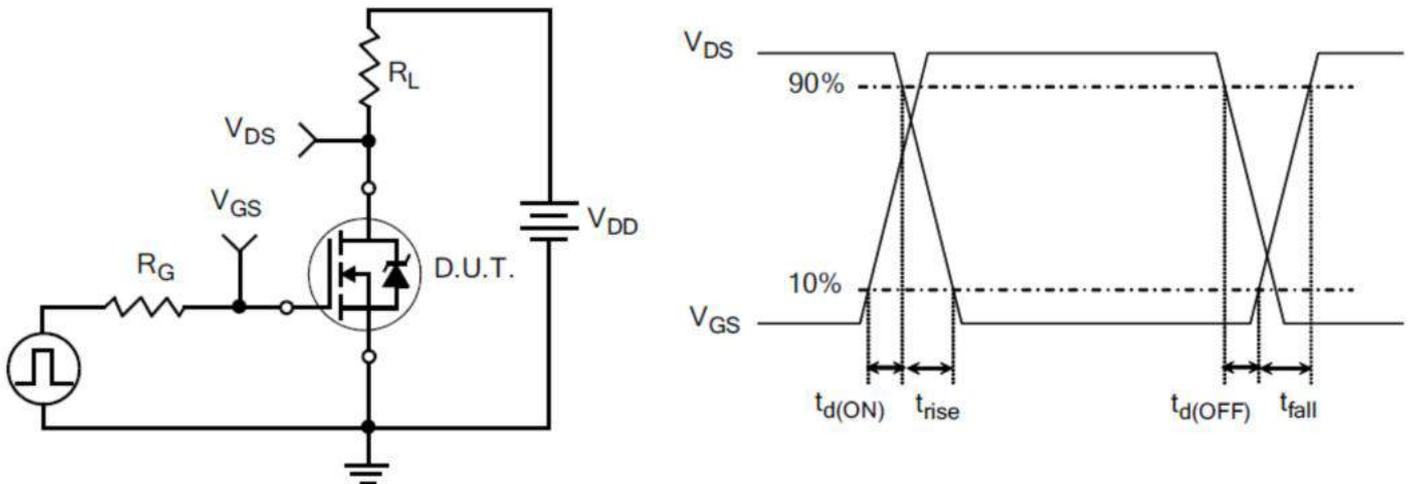
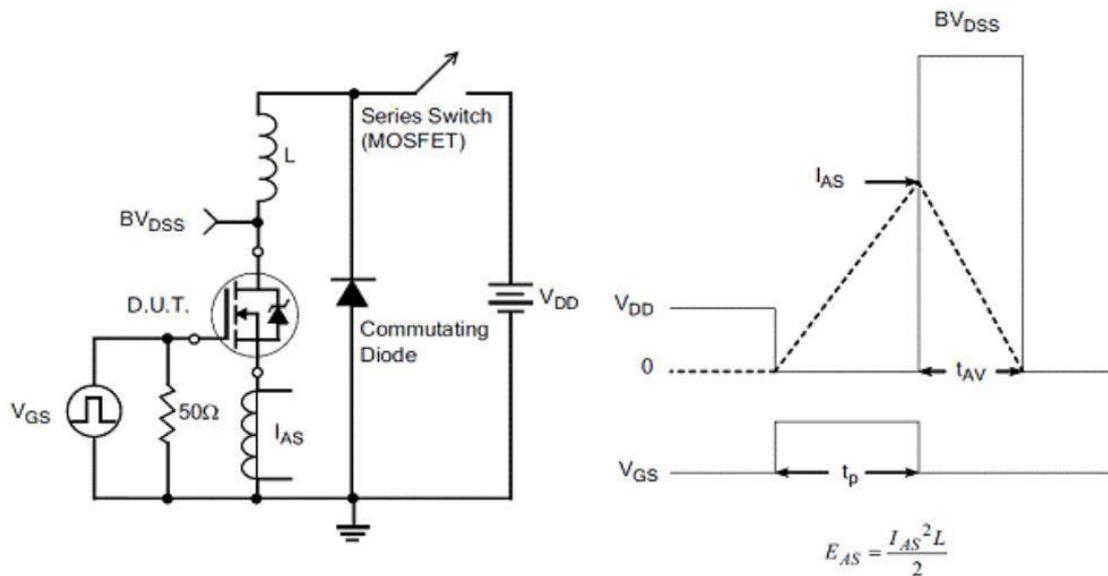
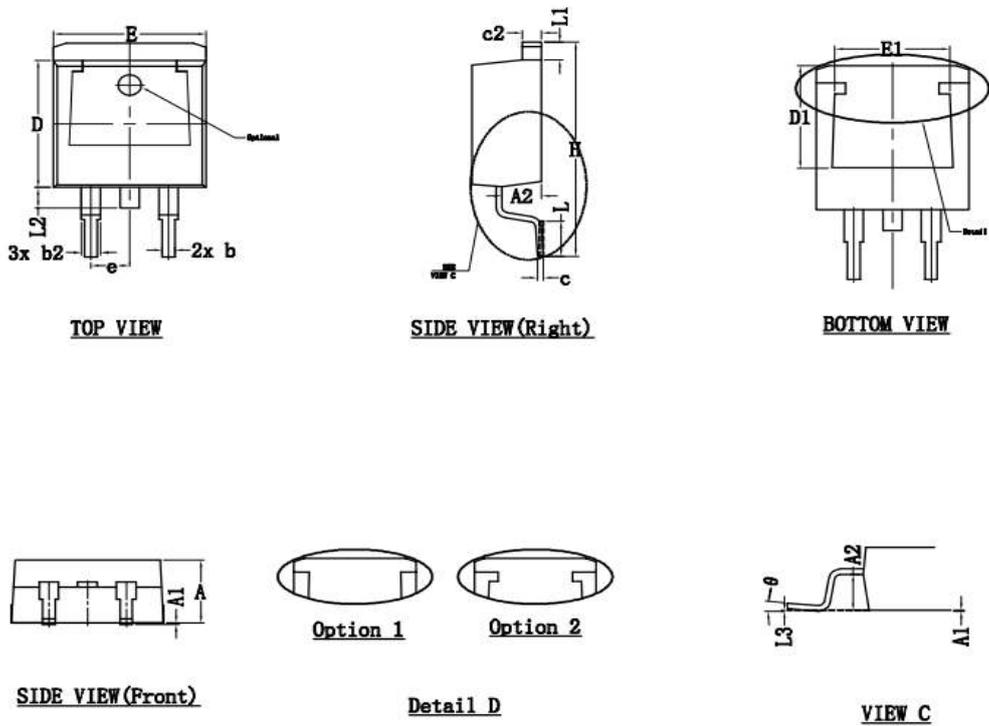


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



## TO-263-2L Package Information



SYMBOL	DIMENSIONS			
	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A	4.30	4.86	0.169	0.191
A1	0.00	0.25	0.00	0.010
A2	2.34	2.79	0.092	0.110
b	0.68	0.94	0.027	0.037
b2	1.15	1.35	0.045	0.053
c	0.33	0.65	0.013	0.026
c2	1.17	1.40	0.046	0.055
D	8.38	9.45	0.330	0.372
D1	6.90	8.17	0.272	0.322
E	9.78	10.50	0.385	0.413
E1	6.50	8.60	0.256	0.339
H	14.61	15.88	0.575	0.625
e	2.54 BSC.		0.100 BSC.	
L	1.78	2.79	0.070	0.110
L1	0.70	1.60	0.028	0.063
L2	1.00	1.78	0.039	0.070
L3	0.254 BSC.		0.010 BSC.	
$\theta$	0°	8°	0.00	0.315

## Customer Service

Sales and Service:

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